



CUSTOMER ADVISORY

ADV2019

Status Update on Stratix® II, Stratix® II GX and Arria® GX Products in Flip Chip with Leaded Bumps (1st level interconnect) Package

Description:

This is a supplemental notification to advisories ADV1828 and ADV2001, to address Stratix® II, Stratix® II GX and Arria® GX products with leaded (SnPb) bumps as 1st level interconnect (die-to-substrate connection).

Table 1

Product Family	Status of Replacement Package with Leadfree SnAg Bumps (ROHS 6 "G" suffix OPN)	Estimated Completion
Stratix II	Package engineering and qualification work in progress.	December 2020**
Stratix II GX		
Arria GX* *except for parts in the next row		**Subject to successful qualification.
Arria GX EP1AGX50C/60C in F484 pins. Part numbers: <ul style="list-style-type: none">• EP1AGX50CF484C6N• EP1AGX50CF484I6N• EP1AGX60CF484C6N• EP1AGX60CF484I6N• EP1AGX50CF484C6	Due to technical limitations, there is no plan to offer replacement "G" products with leadfree bumps. Product Discontinuance PDN2018 issued for these five (5) part numbers: https://www.intel.com/content/dam/www/programmable/us/en/pdfs/literature/pcn/pdn2018.pdf	Not applicable.

Intel will continue to supply Stratix® II, Stratix® II GX and Arria® GX products with leaded bumps (in both leadfree solder ball "N" suffix part numbers and leaded solder

ball part numbers) until the ROHS6 package qualification has been completed and further notification about product availability is provided.

Recommended Action:

It is recommended that customers provide updated forecast information for affected product families to Intel sales to enable Intel's planning for future availability of parts.

Customers should continue to order existing part numbers of Stratix® II, Stratix® II GX and Arria® GX with leaded bumps (in both leadfree solder ball "N" suffix part numbers and leaded solder ball part numbers) until leadfree parts are available.

For customers affected by the discontinuance of the five (5) part numbers of Arria GX listed in Table 1, please refer to PDN2018 for further details:

<https://www.intel.com/content/dam/www/programmable/us/en/pdfs/literature/pcn/pdn2018.pdf>.

Products Affected:

The link below contains the list of affected part numbers (OPNs) with the corresponding leadfree bumps conversion status.

<https://www.intel.com/content/dam/www/programmable/us/en/pdfs/literature/pcn/adv2019-opn-list.xlsx>

Contact

For more information, please contact your Sales representative or submit a Service Request at the [My Intel](#) support page.

Revision History

Date	Rev	Description
05/29/2020	1.0.0	Initial Release

©2020 Intel Corporation. All rights reserved. Intel, the Intel logo, Altera, Arria, Cyclone, Enpirion, Max, Nios, Quartus and Stratix words and logos are trademarks of Intel Corporation or its subsidiaries in the U.S. and/or other countries. Other marks and brands may be claimed as the property of others. Intel reserves the right to make changes to any products and services at any time without notice. Intel assumes no responsibility or liability arising out of the application or use of any information, product, or service described herein except as expressly agreed to in writing by Intel. Intel customers are advised to obtain the latest version of device specifications before relying on any published information and before placing orders for products or services.